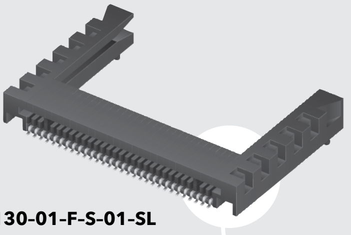
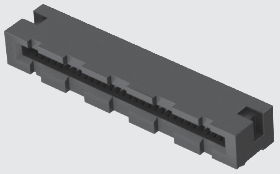
**samtec**



MB1-130-01-F-S-01-SL



MB1-130-01-F-S-01-SL-N

**(1.00 mm) .0394"**

**MB1 SERIES**

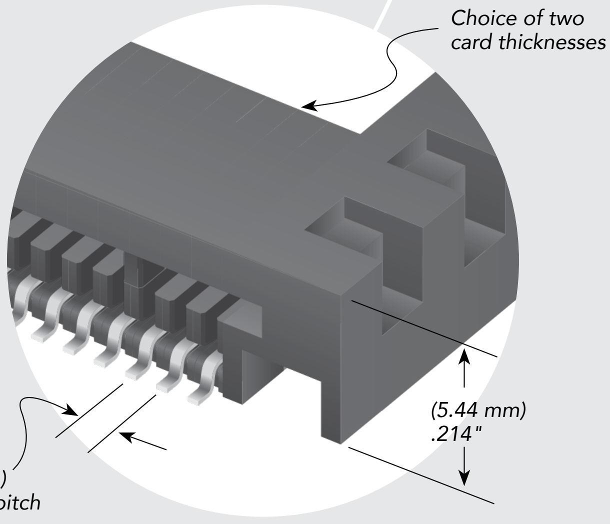
# MINI EDGE CARD SOCKET WITH GUIDES

## SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?MB1

**Insulator Material:**
Black LCP
**Contact Material:**
BeCu
**Plating:**
Sn or Au over
50 µ" (1.27 µm) Ni
**Current Rating:**
2.4 A per pin
(2 pins powered)
**Voltage Rating:**
250 VDC/354 VDC
**Operating Temp Range:**
-55 °C to +125 °C
**Insertion Depth:**
(5.26 mm) .207" to
(6.10 mm) .240"
**RoHS Compliant:**
Yes

**Mates with:**
(0.80 mm) .031" PCB,
(1.60 mm) .062" PCB



## PROCESSING

**Lead-Free Solderable:**
Yes
**SMT Lead Coplanarity:**
(0.10 mm) .004" max (20-30)
(0.15 mm) .006" max (40-50)*
*(.004" stencil solution may be available; contact ipg@samtec.com)

## RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality

FILE NO. E111594

## ALSO AVAILABLE
**(MOQ Required)**

- Other platings

**MB1** – **1** – **NO. OF PINS** – **01** – **PLATING OPTION** – **S** – **CARD SLOT** – **SL** – **OTHER OPTION**

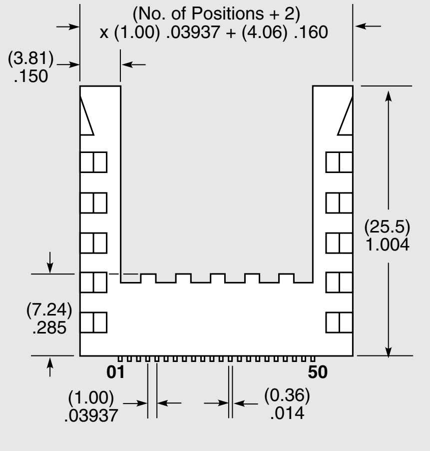
**NO. OF PINS**
**20, 30, 40, 50**

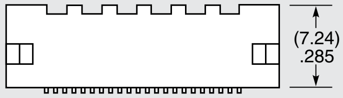
**PLATING OPTION**
**-F**
**= Gold flash on contact, Matte Tin on tail**
**-L**
**= 10 µ" (0.25 µm) Gold on contact, Matte Tin on tail**

**CARD SLOT**
**Specify CARD SLOT from chart**

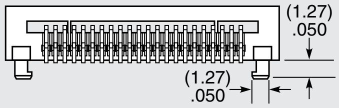
**OTHER OPTION**
**–N**
**= No Card Guides**

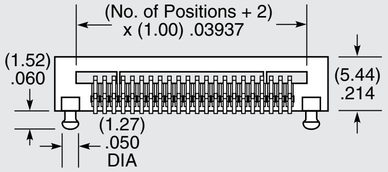
| CARD SLOT | A | MATES WITH BOARD THICKNESS |
|---|---|---|
| **-01** | (0.97)<br>.038 | (0.80) .031 |
| **-02** | (1.83)<br>.072 | (1.60) .062 |

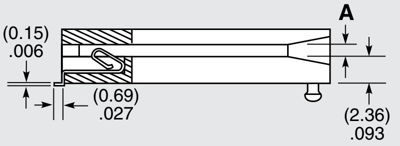




**-N OPTION**







**Important Note:** Samtec recommends that pads on the mating board be Gold plated.

**Note:**
Some sizes, styles and options are non-standard, non-returnable.